



FAN3226 / FAN3227 / FAN3228 / FAN3229

Dual 2A High-Speed, Low-Side Gate Drivers

Features

- Industry-Standard Pinouts
- 4.5 to 18V Operating Range
- 3A Peak Sink/Source at $V_{DD} = 12V$
- 2.4A Sink / 1.6A Source at $V_{OUT} = 6V$
- Choice of TTL or CMOS Input Thresholds
- Four Logic Versions of Dual Independent Drivers:
 - Dual Inverting + Enable (FAN3226)
 - Dual Non-Inverting + Enable (FAN3227)
 - Dual-Inputs in Pin Configuration 1 (FAN3228)
 - Dual-Inputs in Pin Configuration 2 (FAN3229)
- Internal Resistors Turn Driver Off If No Inputs
- MillerDrive™ Technology
- 12ns / 9ns Typical Rise/Fall Times with 1nF Load
- Typical Propagation Delay Under 20ns Matched within 1ns to the Other Channel
- Double Current Capability by Paralleling Channels
- 8-Lead 3x3mm MLP or 8-Lead SOIC Package
- Rated from $-40^{\circ}C$ to $+125^{\circ}C$ Ambient

Applications

- Switch-Mode Power Supplies
- High-Efficiency MOSFET Switching
- Synchronous Rectifier Circuits
- DC-to-DC Converters
- Motor Control

Description

The FAN3226-29 family of dual 2A gate drivers is designed to drive N-channel enhancement-mode MOSFETs in low-side switching applications by providing high peak current pulses during the short switching intervals. The driver is available with either TTL or CMOS input thresholds. Internal circuitry provides an under-voltage lockout function by holding the output low until the supply voltage is within the operating range. In addition, the drivers feature matched internal propagation delays between A and B channels for applications requiring dual gate drives with critical timing, such as synchronous rectifiers. This enables connecting two drivers in parallel to effectively double the current capability driving a single MOSFET.

The FAN322X drivers incorporate MillerDrive™ architecture for the final output stage. This bipolar-MOSFET combination provides high current during the Miller plateau stage of the MOSFET turn-on / turn-off process to minimize switching loss, while providing rail-to-rail voltage swing and reverse current capability.

The FAN3226 offers two inverting drivers and the FAN3227 offers two non-inverting drivers. Each device has dual independent enable pins that default to ON if not connected. In the FAN3228 and FAN3229, each channel has dual inputs of opposite polarity, which allows configuration as non-inverting or inverting with an optional enable function using the second input. If one or both inputs are left unconnected, internal resistors bias the inputs such that the output is pulled low to hold the power MOSFET off.

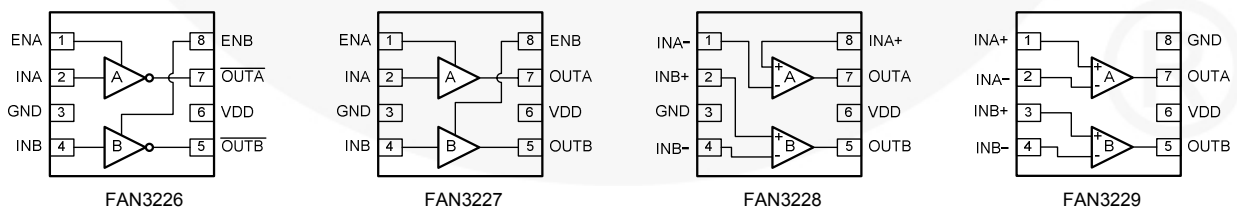



Figure 1. Pin Configurations

Ordering Information

Part Number	Logic	Input Threshold	Package	Packing Method	Quantity per Reel
FAN3226CMPX	Dual Inverting Channels + Dual Enable	CMOS	3x3mm MLP-8	Tape & Reel	3,000
FAN3226CMX			SOIC-8	Tape & Reel	2,500
FAN3226TMPX		TTL	3x3mm MLP-8	Tape & Reel	3,000
FAN3226TMX			SOIC-8	Tape & Reel	2,500
FAN3227CMPX	Dual Non-Inverting Channels + Dual Enable	CMOS	3x3mm MLP-8	Tape & Reel	3,000
FAN3227CMX			SOIC-8	Tape & Reel	2,500
FAN3227TMPX		TTL	3x3mm MLP-8	Tape & Reel	3,000
FAN3227TMX			SOIC-8	Tape & Reel	2,500
FAN3228CMPX	Dual Channels of Two-Input / One-Output Drivers, Pin Configuration 1	CMOS	3x3mm MLP-8	Tape & Reel	3,000
FAN3228CMX			SOIC-8	Tape & Reel	2,500
FAN3228TMPX		TTL	3x3mm MLP-8	Tape & Reel	3,000
FAN3228TMX			SOIC-8	Tape & Reel	2,500
FAN3229CMPX	Dual Channels of Two-Input / One-Output Drivers, Pin Configuration 2	CMOS	3x3mm MLP-8	Tape & Reel	3,000
FAN3229CMX			SOIC-8	Tape & Reel	2,500
FAN3229TMPX		TTL	3x3mm MLP-8	Tape & Reel	3,000
FAN3229TMX			SOIC-8	Tape & Reel	2,500

 All packages are lead free per JEDEC: J-STD-020B standard.

Package Outlines

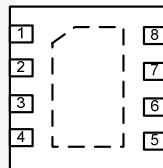


Figure 2. 3x3mm MLP-8 (Top View)

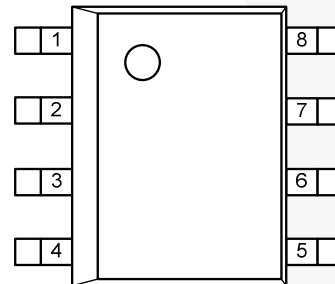


Figure 3. SOIC-8 (Top View)

Thermal Characteristics⁽¹⁾

Package	Θ_{JL} ⁽²⁾	Θ_{JT} ⁽³⁾	Θ_{JA} ⁽⁴⁾	Ψ_{JB} ⁽⁵⁾	Ψ_{JT} ⁽⁶⁾	Units
8-Lead 3x3mm Molded Leadless Package (MLP)	1.6	68	43	3.5	0.8	°C/W
8-Pin Small Outline Integrated Circuit (SOIC)	40	31	89	43	3.0	°C/W

Notes:

- Estimates derived from thermal simulation; actual values depend on the application.
- Θ_{JL} (Θ_{JL}): Thermal resistance between the semiconductor junction and the bottom surface of all the leads (including any thermal pad) that are typically soldered to a PCB.
- Θ_{JT} (Θ_{JT}): Thermal resistance between the semiconductor junction and the top surface of the package, assuming it is held at a uniform temperature by a top-side heatsink.
- Θ_{JA} (Θ_{JA}): Thermal resistance between junction and ambient, dependent on the PCB design, heat sinking, and airflow. The value given is for natural convection with no heatsink, as specified in JEDEC standards JESD51-2, JESD51-5, and JESD51-7, as appropriate.
- Ψ_{JB} (Ψ_{JB}): Thermal characterization parameter providing correlation between semiconductor junction temperature and an application circuit board reference point for the thermal environment defined in Note 4. For the MLP-8 package, the board reference is defined as the PCB copper connected to the thermal pad and protruding from either end of the package. For the SOIC-8 package, the board reference is defined as the PCB copper adjacent to pin 6.
- Ψ_{JT} (Ψ_{JT}): Thermal characterization parameter providing correlation between the semiconductor junction temperature and the center of the top of the package for the thermal environment defined in Note 4.

Pin Configurations

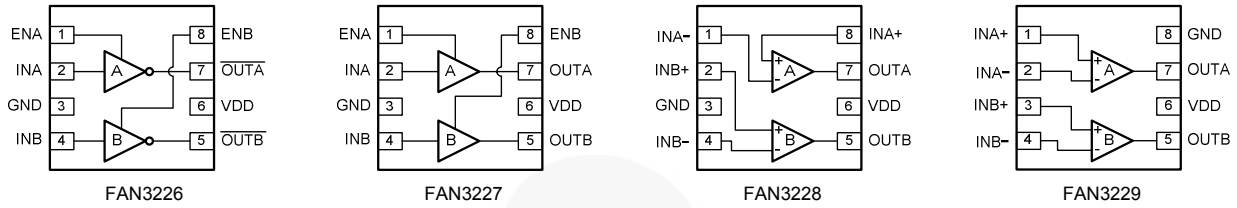


Figure 4. Pin Assignments

Pin Definitions

Name	Pin Description
ENA	Enable Input for Channel A. Pull pin low to inhibit driver A. ENA has TTL thresholds for both TTL and CMOS INx threshold.
ENB	Enable Input for Channel B. Pull pin low to inhibit driver B. ENB has TTL thresholds for both TTL and CMOS INx threshold.
GND	Ground. Common ground reference for input and output circuits.
INA	Input to Channel A.
INA+	Non-Inverting Input to Channel A. Connect to V _{DD} to enable output.
INA-	Inverting Input to Channel A. Connect to GND to enable output.
INB	Input to Channel B.
INB+	Non-Inverting Input to Channel B. Connect to V _{DD} to enable output.
INB-	Inverting Input to Channel B. Connect to GND to enable output.
OUTA	Gate Drive Output A: Held low unless required input(s) are present and V _{DD} is above UVLO threshold.
OUTB	Gate Drive Output B: Held low unless required input(s) are present and V _{DD} is above UVLO threshold.
$\overline{\text{OUTA}}$	Gate Drive Output A (inverted from the input): Held low unless required input is present and V _{DD} is above UVLO threshold.
$\overline{\text{OUTB}}$	Gate Drive Output B (inverted from the input): Held low unless required input is present and V _{DD} is above UVLO threshold.
P1	Thermal Pad (MLP only). Exposed metal on the bottom of the package; may be left floating or connected to GND; NOT suitable for carrying current.
VDD	Supply Voltage. Provides power to the IC.

Output Logic

FAN3226 (x=A or B)		
ENx	INx	$\overline{\text{OUTx}}$
0	0	0
0	1 ⁽⁷⁾	0
1 ⁽⁷⁾	0	1
1 ⁽⁷⁾	1 ⁽⁷⁾	0

FAN3227 (x=A or B)		
ENx	INx	OUTx
0	0 ⁽⁷⁾	0
0	1	0
1 ⁽⁷⁾	0 ⁽⁷⁾	0
1 ⁽⁷⁾	1	1

FAN3228 and FAN3229 (x=A or B)		
INx+	INx-	OUTx
0 ⁽⁷⁾	0	0
0 ⁽⁷⁾	1 ⁽⁷⁾	0
1	0	1
1	1 ⁽⁷⁾	0

Note:

7. Default input signal if no external connection is made.

Block Diagrams

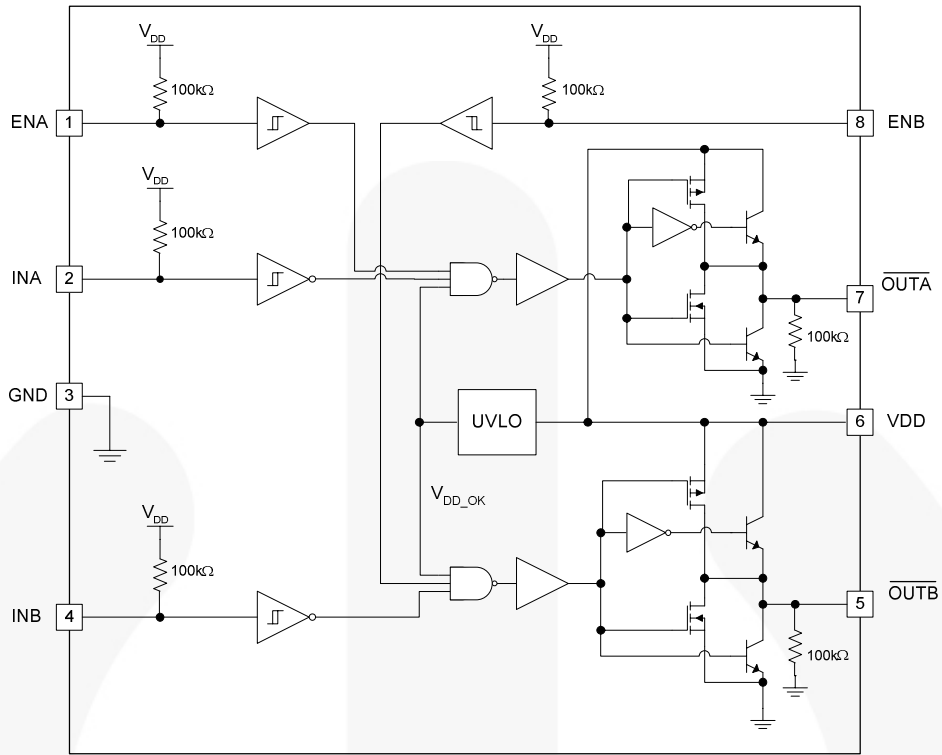


Figure 5. FAN3226 Block Diagram

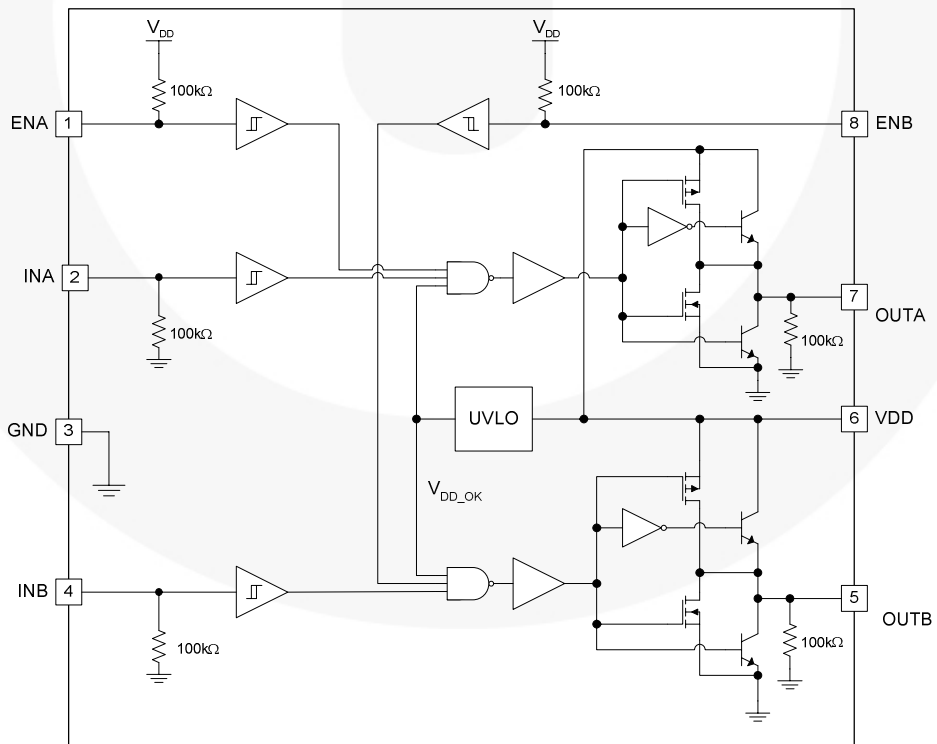


Figure 6. FAN3227 Block Diagram

Block Diagrams

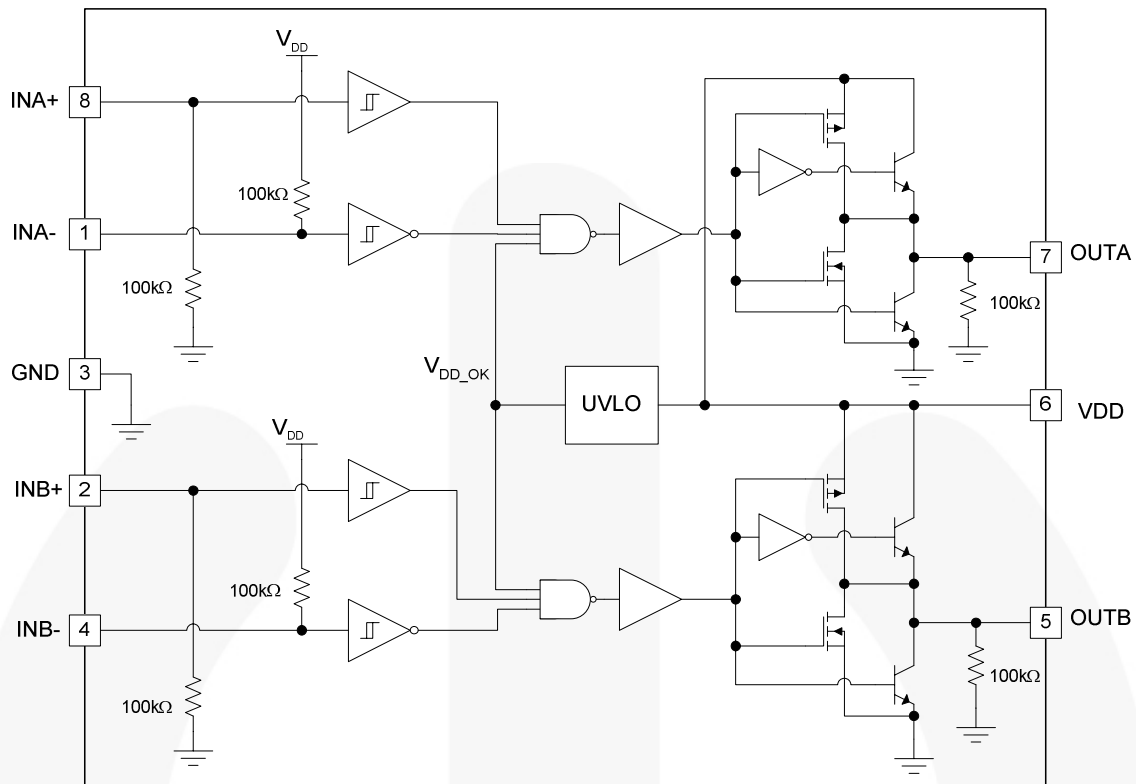


Figure 7. FAN3228 Block Diagram

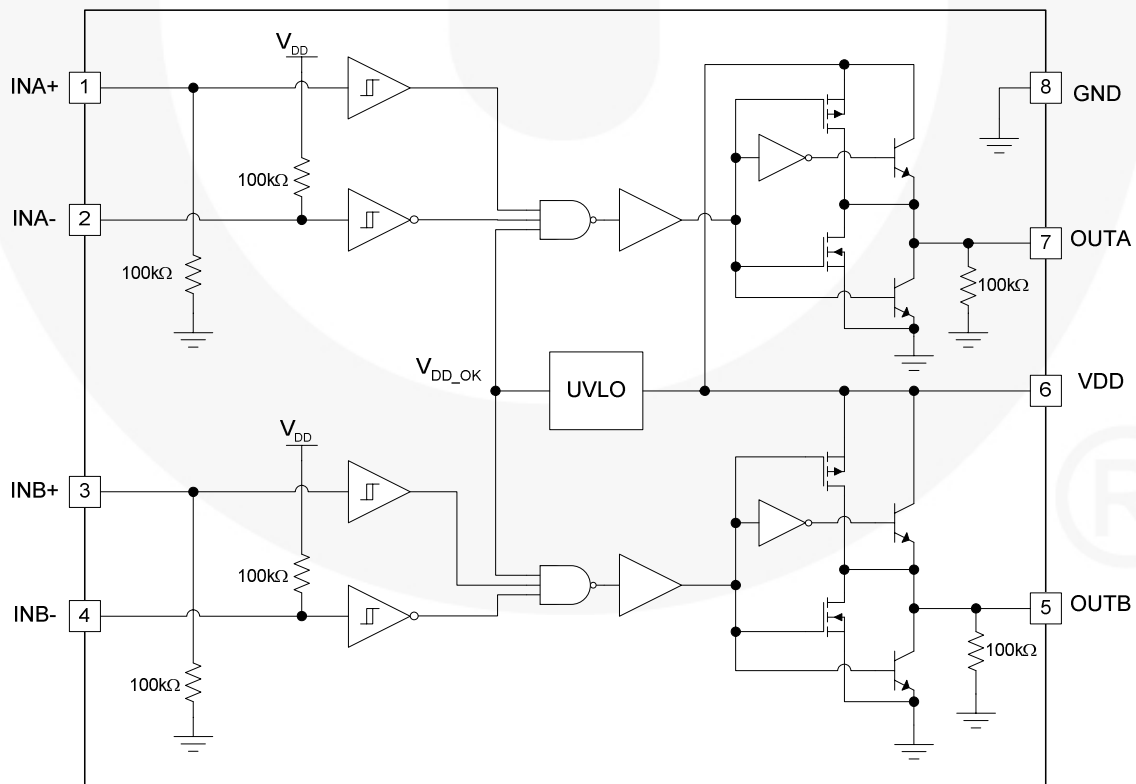


Figure 8. FAN3229 Block Diagram

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V _{DD}	VDD to PGND		-0.3	20.0	V
V _{EN}	ENA and ENB to GND		GND - 0.3	V _{DD} + 0.3	V
V _{IN}	INA, INA+, INA-, INB, INB+ and INB- to GND		GND - 0.3	V _{DD} + 0.3	V
V _{OUT}	OUTA and OUTB to GND		GND - 0.3	V _{DD} + 0.3	V
T _L	Lead Soldering Temperature (10 Seconds)			+260	°C
T _J	Junction Temperature			+150	°C
T _{STG}	Storage Temperature		-65	+150	°C
ESD	Electrostatic Discharge Protection Level	Human Body Model, JEDEC JESD22-A114	4		kV
		Charged Device Model, JEDEC JESD22-C101	1		kV

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter		Min.	Max.	Unit
V _{DD}	Supply Voltage Range		4.5	18.0	V
V _{EN}	Enable Voltage ENA and ENB		0	V _{DD}	V
V _{IN}	Input Voltage INA, INA+, INA-, INB, INB+ and INB-		0	V _{DD}	V
T _A	Operating Ambient Temperature		-40	+125	°C

Electrical Characteristics

Unless otherwise noted, $V_{DD}=12V$, $T_J=-40^{\circ}C$ to $+125^{\circ}C$. Currents are defined as positive into the device and negative out of the device.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Supply						
V_{DD}	Operating Range		4.5		18.0	V
I_{DD}	Supply Current Inputs / EN Not Connected	TTL		0.67	0.95	mA
		CMOS		0.56	0.80	mA
V_{ON}	Turn-On Voltage	INA=ENA=V _{DD} , INB=ENB=0V	3.5	3.9	4.3	V
V_{OFF}	Turn-Off Voltage	INA=ENA=V _{DD} , INB=ENB=0V	3.3	3.7	4.1	V
Inputs (FAN322xT)⁽⁸⁾						
V_{IL_T}	INx Logic Low Threshold		0.8	1.2		V
V_{IH_T}	INx Logic High Threshold			1.6	2.0	V
I_{IN+}	Non-inverting Input	IN from 0 to V _{DD}	-1.5		175.0	μA
I_{IN-}	Inverting Input	IN from 0 to V _{DD}	-175.0		1.5	μA
V_{HYS_T}	TTL Logic Hysteresis Voltage		0.2	0.4	0.8	V
Inputs (FAN322xC)⁽⁸⁾						
V_{IL_C}	INx Logic Low Threshold		30	38		%V _{DD}
V_{IH_C}	INx Logic High Threshold			55	70	%V _{DD}
I_{INL}	IN Current, Low	IN from 0 to V _{DD}	-1		175	μA
I_{INH}	IN Current, High	IN from 0 to V _{DD}	-175		1	μA
V_{HYS_C}	CMOS Logic Hysteresis Voltage			17		%V _{DD}
ENABLE (FAN3226C, FAN3226T, FAN3227C, FAN3227T)						
V_{ENL}	Enable Logic Low Threshold	EN from 5V to 0V	0.8	1.2		V
V_{ENH}	Enable Logic High Threshold	EN from 0V to 5V		1.6	2.0	V
V_{HYS_T}	TTL Logic Hysteresis Voltage ⁽⁹⁾			0.4		V
R_{PU}	Enable Pull-up Resistance ⁽⁹⁾			100		kΩ
t_{D1}, t_{D2}	Propagation Delay, EN Rising ⁽¹⁰⁾	0 - 5V _{IN} , 1V/ns Slew Rate	7	14	21	ns
t_{D1}, t_{D2}	Propagation Delay, EN Falling ⁽¹⁰⁾	0 - 5V _{IN} , 1V/ns Slew Rate	10	19	30	ns

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Electrical Characteristics (Continued)

Unless otherwise noted, $V_{DD}=12V$, $T_J=-40^{\circ}C$ to $+125^{\circ}C$. Currents are defined as positive into the device and negative out of the device.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Output						
I_{SINK}	OUT Current, Mid-Voltage, Sinking ⁽⁹⁾	OUT at $V_{DD}/2$, $C_{LOAD}=0.1\mu F$, $f=1kHz$		2.4		A
I_{SOURCE}	OUT Current, Mid-Voltage, Sourcing ⁽⁹⁾	OUT at $V_{DD}/2$, $C_{LOAD}=0.1\mu F$, $f=1kHz$		-1.6		A
I_{PK_SINK}	OUT Current, Peak, Sinking ⁽⁹⁾	$C_{LOAD}=0.1\mu F$, $f=1kHz$		3		A
I_{PK_SOURCE}	OUT Current, Peak, Sourcing ⁽⁹⁾	$C_{LOAD}=0.1\mu F$, $f=1kHz$		-3		A
t_{RISE}	Output Rise Time ⁽¹⁰⁾	$C_{LOAD}=1000pF$		12	20	ns
t_{FALL}	Output Fall Time ⁽¹⁰⁾	$C_{LOAD}=1000pF$		9	15	ns
t_{D1}, t_{D2}	Output Propagation Delay, CMOS Inputs ⁽¹⁰⁾	0 - $12V_{IN}$, 1V/ns Slew Rate	6	15	29	ns
t_{D1}, t_{D2}	Output Propagation Delay, TTL Inputs ⁽¹⁰⁾	0 - $5V_{IN}$, 1V/ns Slew Rate	7	16	30	ns
	Propagation Matching Between Channels	$INA=INB$, $OUTA$ and $OUTB$ at 50% point		1	2	ns
I_{RVS}	Output Reverse Current Withstand ⁽⁹⁾			500		mA

Notes:

- 8. EN inputs have TTL thresholds; refer to the ENABLE section.
- 9. Not tested in production.
- 10. See Timing Diagrams of Figure 9 and Figure 10.

Timing Diagrams

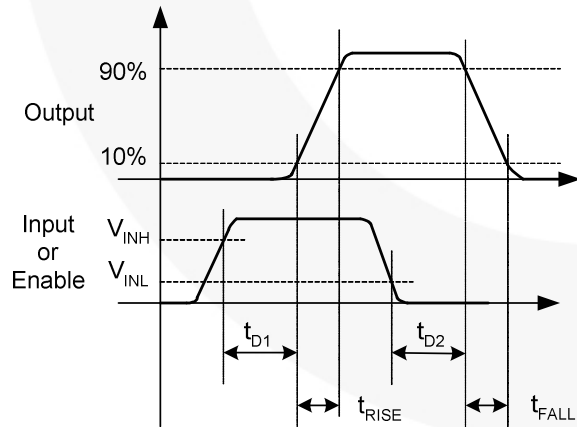


Figure 9. Non-inverting

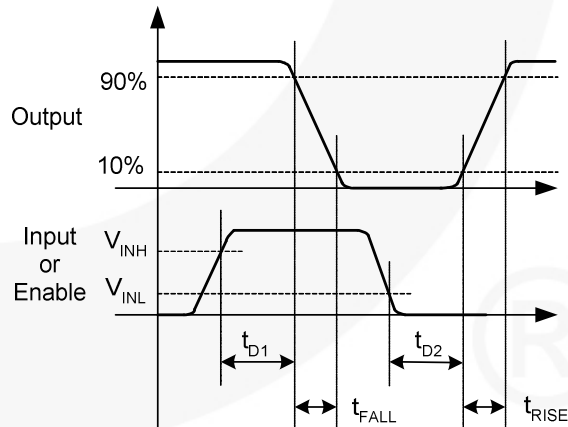


Figure 10. Inverting

Typical Performance Characteristics

Typical characteristics are provided at 25°C and $V_{DD}=12V$ unless otherwise noted.

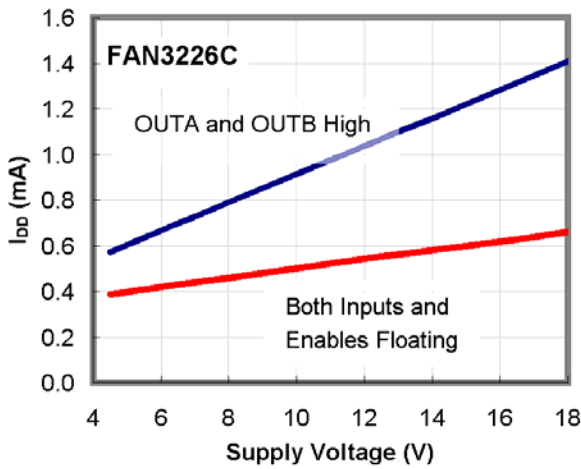


Figure 11. I_{DD} (Static) vs. Supply Voltage

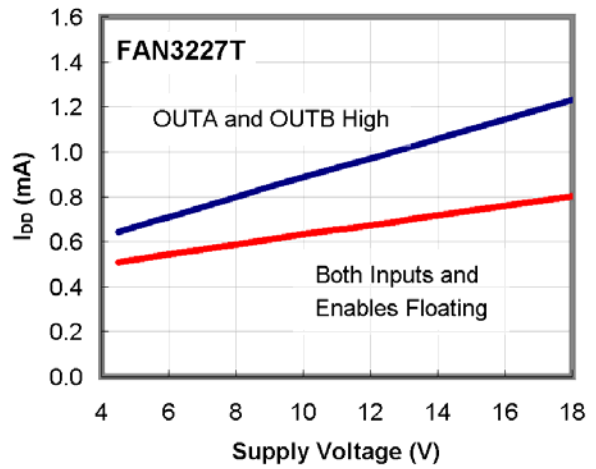


Figure 12. I_{DD} (Static) vs. Supply Voltage

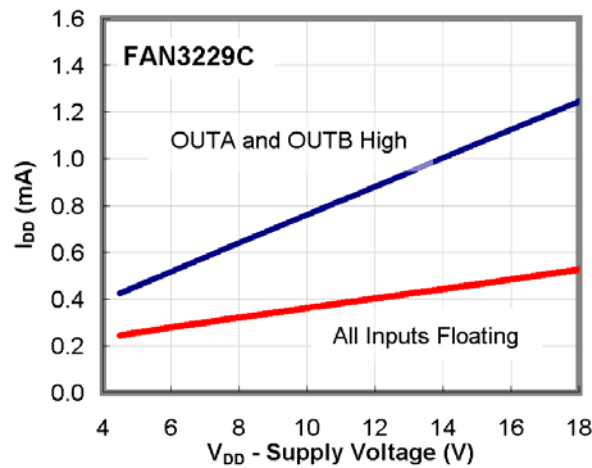


Figure 13. I_{DD} (Static) vs. Supply Voltage

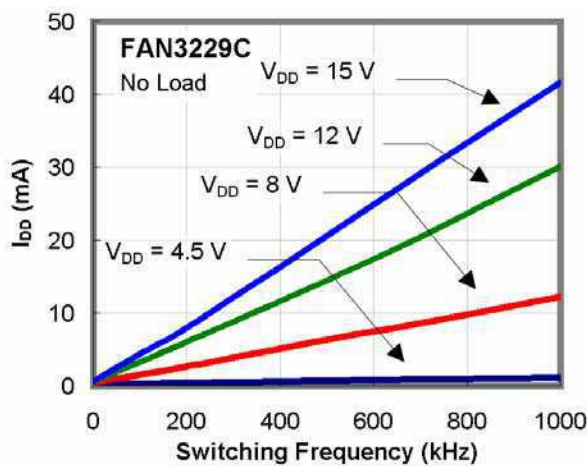


Figure 14. I_{DD} (No-Load) vs. Frequency

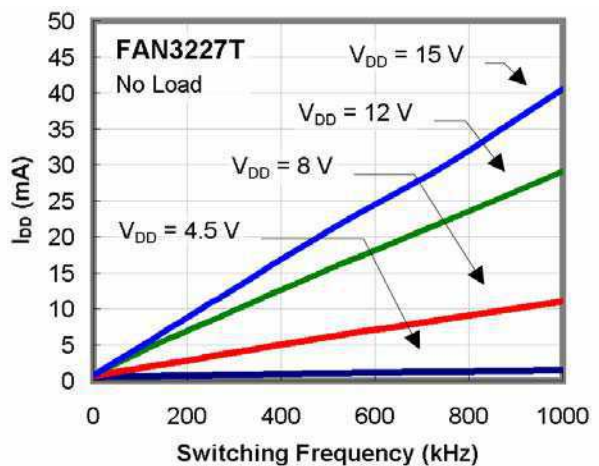


Figure 15. I_{DD} (No-Load) vs. Frequency

Typical Performance Characteristics

Typical characteristics are provided at 25°C and $V_{DD}=12V$ unless otherwise noted.

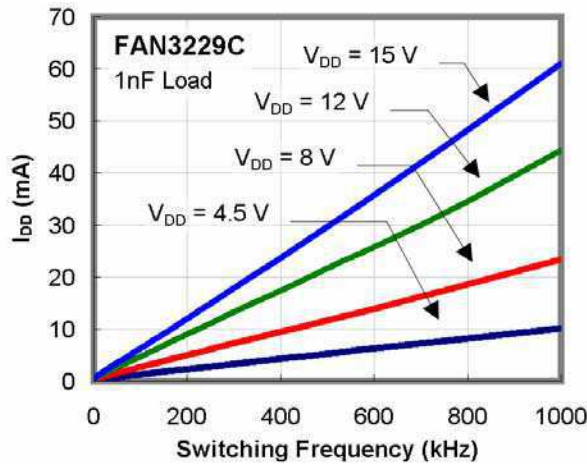


Figure 16. IDD (1nF Load) vs. Frequency

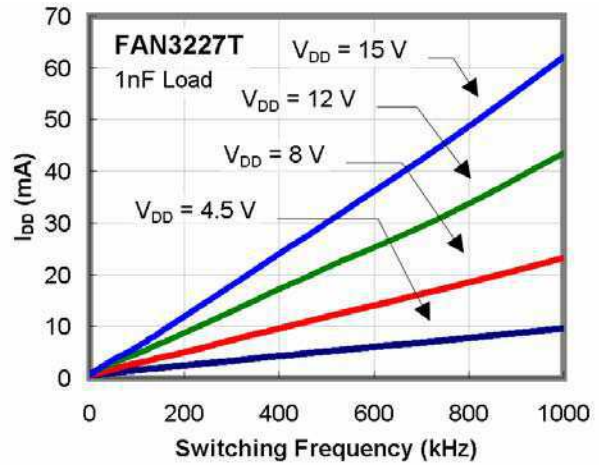


Figure 17. IDD (1nF Load) vs. Frequency

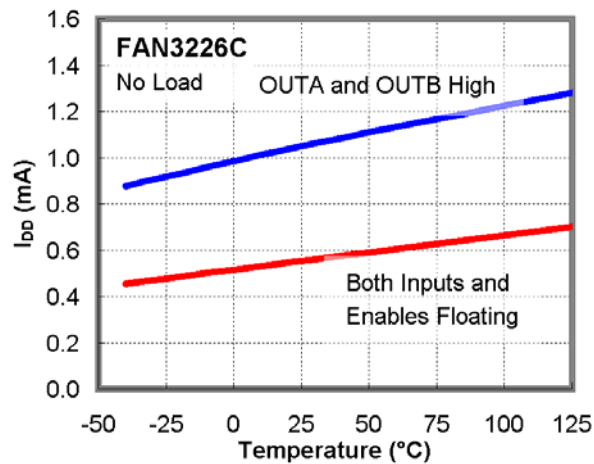


Figure 18. IDD (Static) vs. Temperature

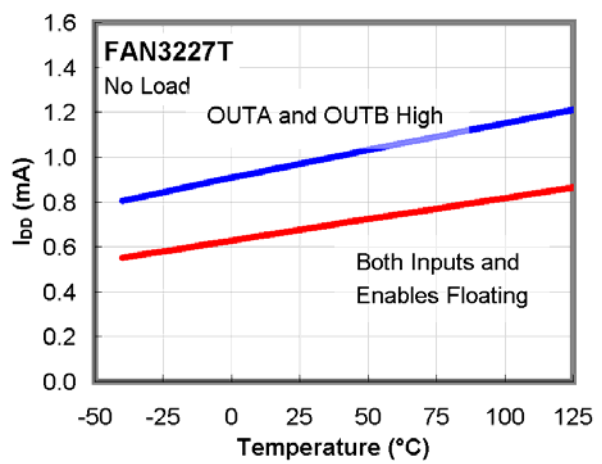


Figure 19. IDD (Static) vs. Temperature

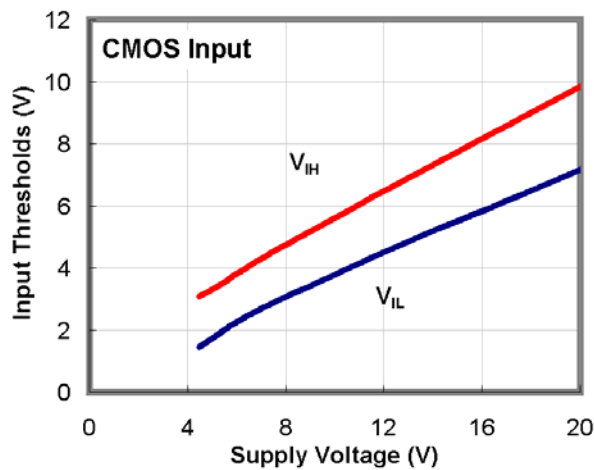


Figure 20. Input Thresholds vs. Supply Voltage

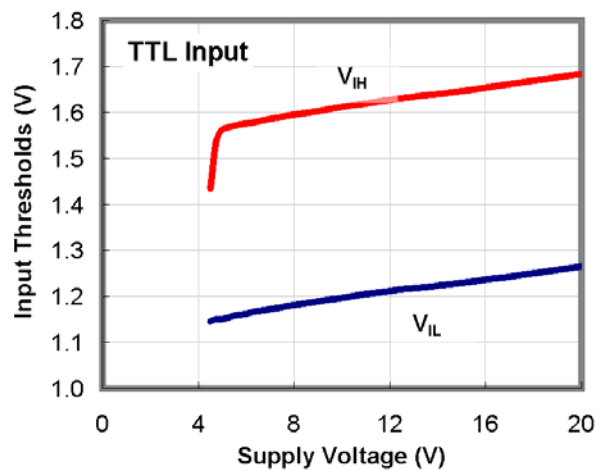


Figure 21. Input Thresholds vs. Supply Voltage

Typical Performance Characteristics

Typical characteristics are provided at 25°C and $V_{DD}=12V$ unless otherwise noted.

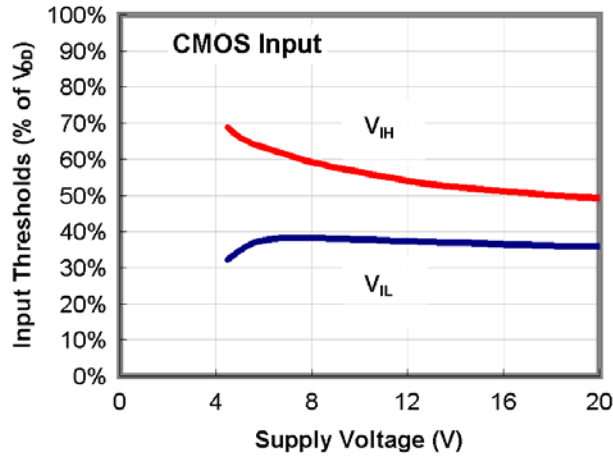


Figure 22. Input Threshold % vs. Supply Voltage

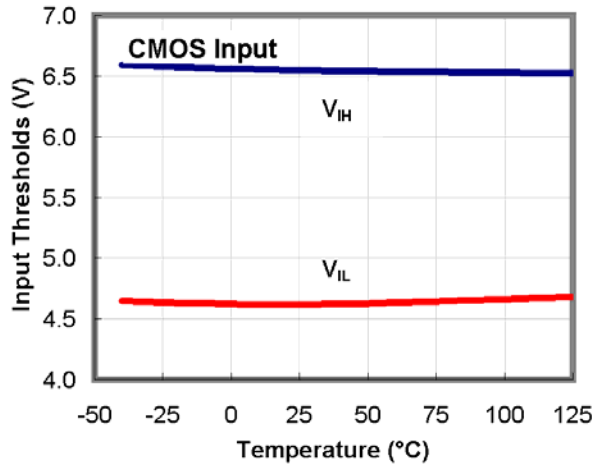


Figure 23. Input Thresholds vs. Temperature

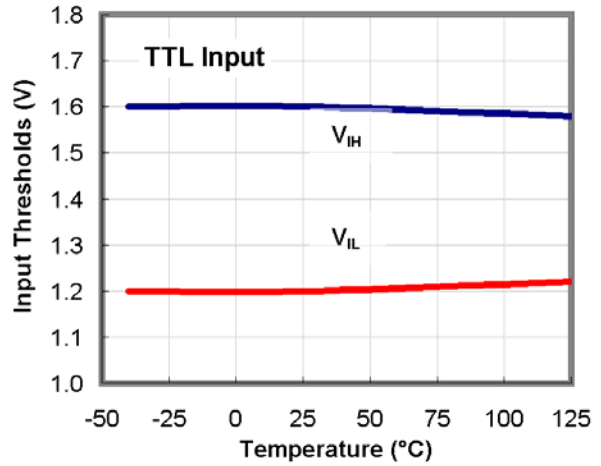


Figure 24. Input Thresholds vs. Temperature

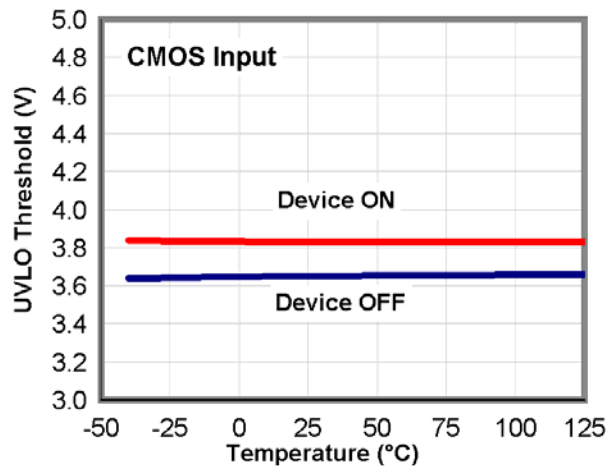


Figure 25. UVLO Thresholds vs. Temperature

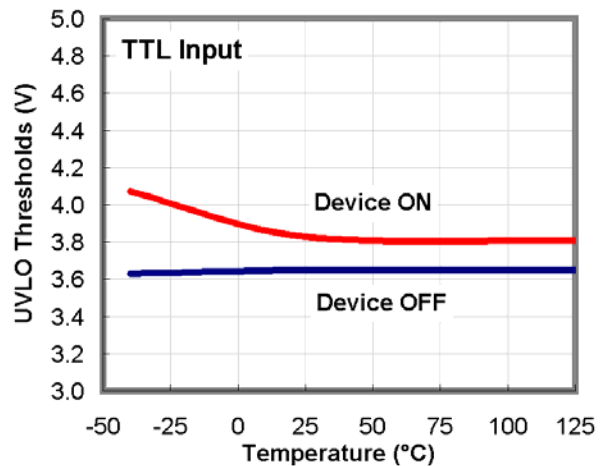


Figure 26. UVLO Threshold vs. Temperature

Typical Performance Characteristics

Typical characteristics are provided at 25°C and $V_{DD}=12V$ unless otherwise noted.

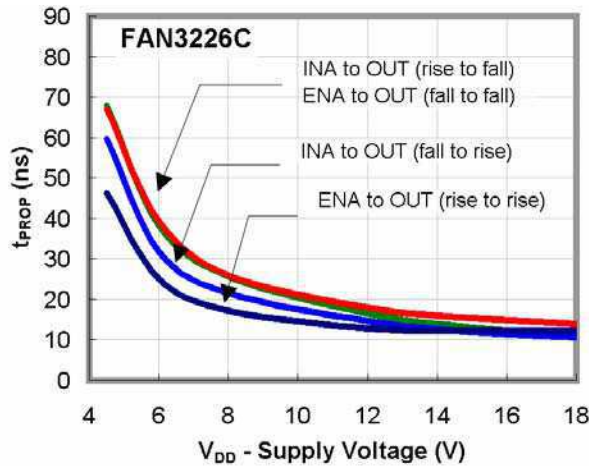


Figure 27. Propagation Delays vs. Supply Voltage

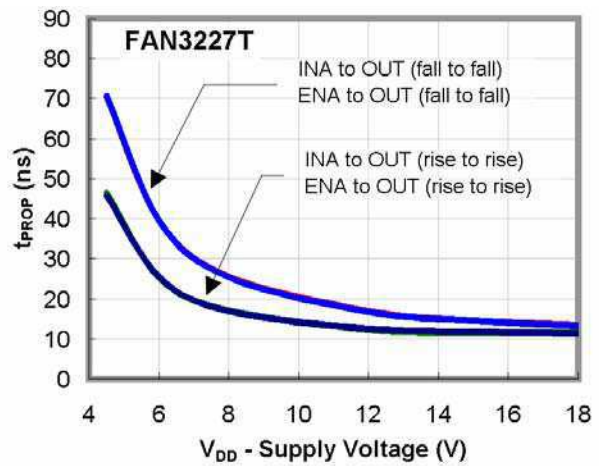


Figure 28. Propagation Delays vs. Supply Voltage

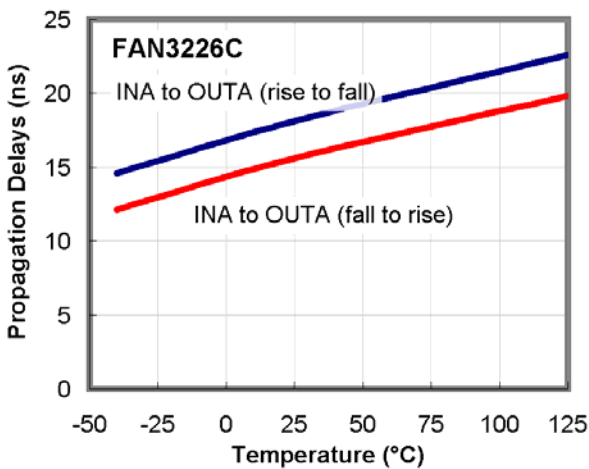


Figure 29. Propagation Delays vs. Temperature

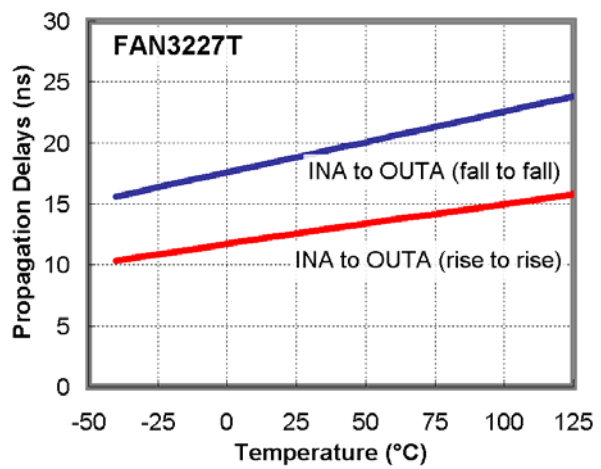


Figure 30. Propagation Delays vs. Temperature

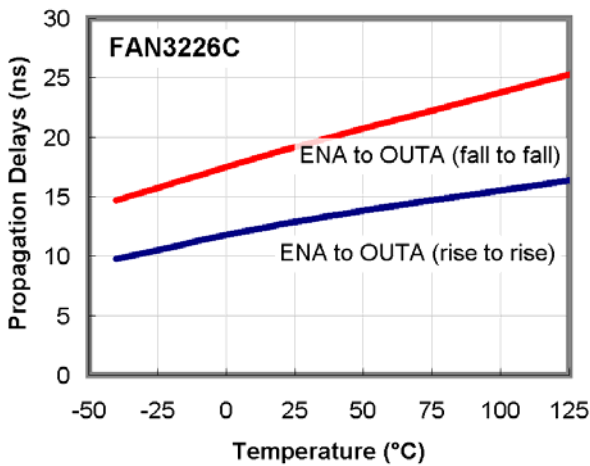


Figure 31. Propagation Delay vs. Temperature

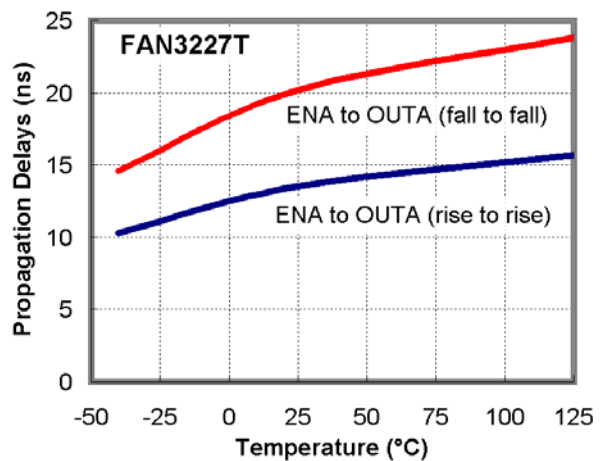


Figure 32. Propagation Delay vs. Temperature

Typical Performance Characteristics

Typical characteristics are provided at 25°C and $V_{DD}=12V$ unless otherwise noted.

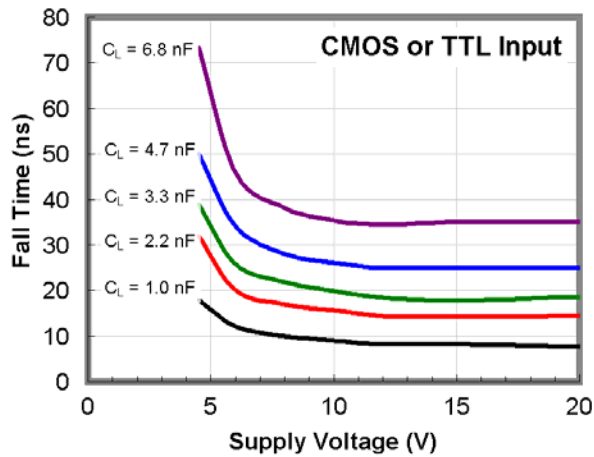


Figure 33. Fall Time vs. Supply Voltage

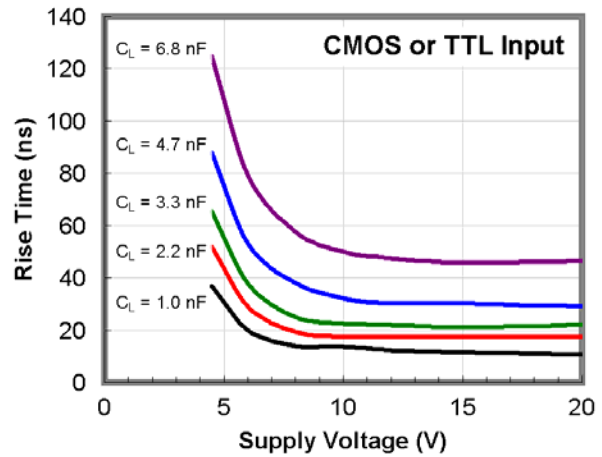


Figure 34. Rise Time vs. Supply Voltage

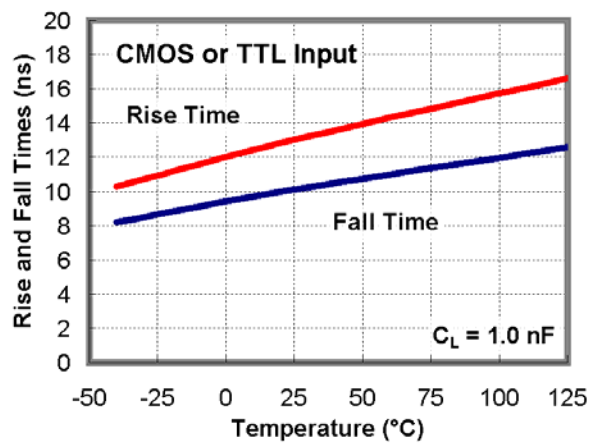


Figure 35. Rise and Fall Times vs. Temperature

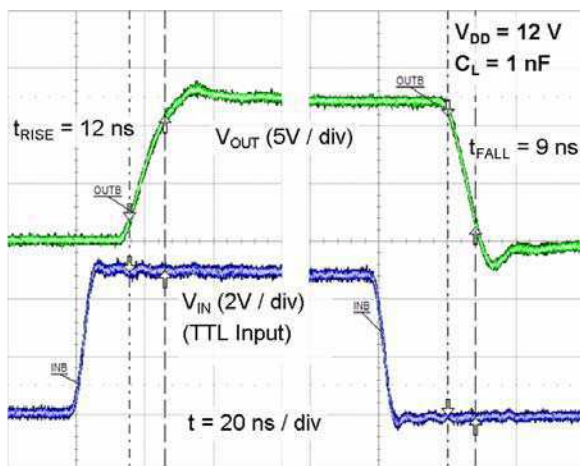


Figure 36. Rise/Fall Waveforms with 1nF Load

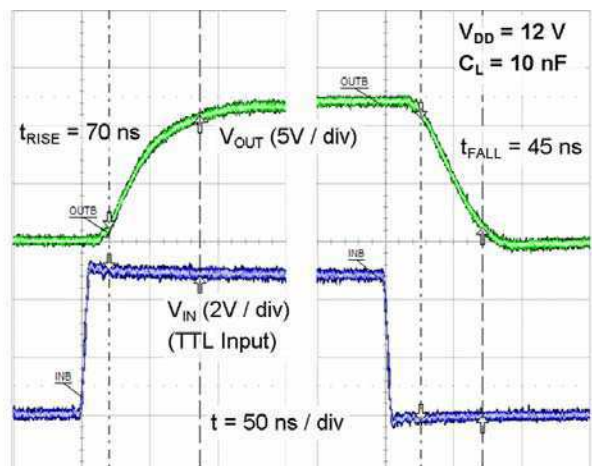


Figure 37. Rise/Fall Waveforms with 10nF Load

Typical Performance Characteristics

Typical characteristics are provided at 25°C and $V_{DD}=12V$ unless otherwise noted.

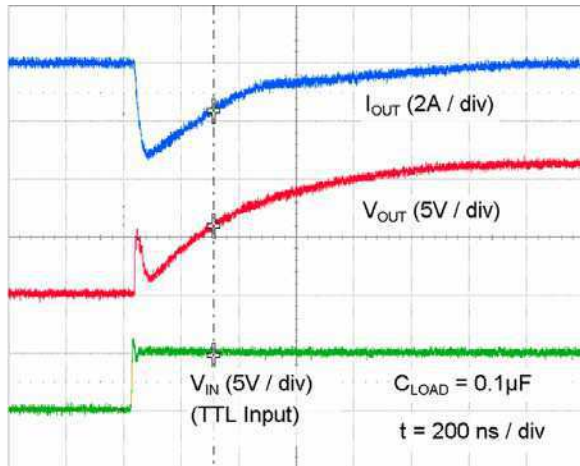


Figure 38. Quasi-Static Source Current with $V_{DD}=12V$

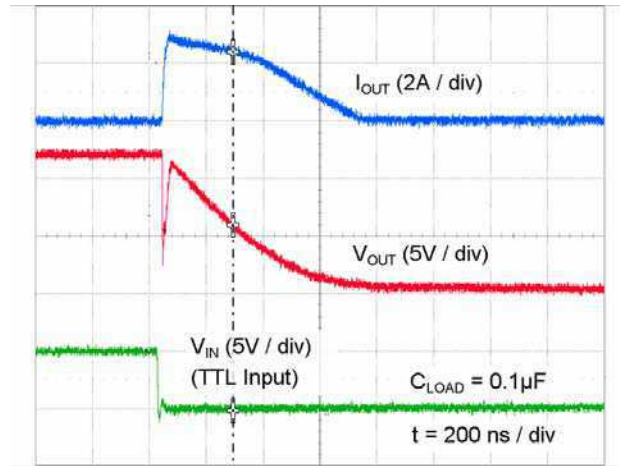


Figure 39. Quasi-Static Sink Current with $V_{DD}=12V$

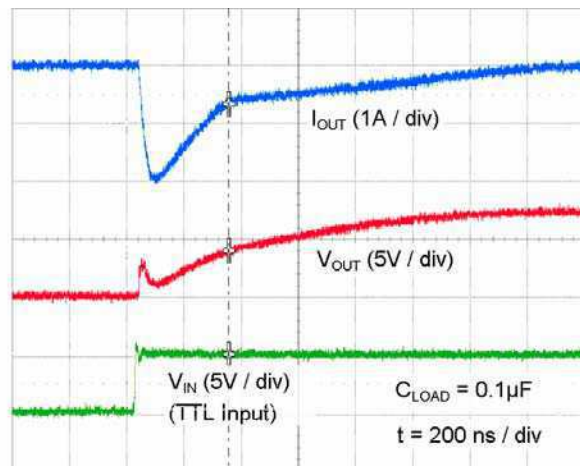


Figure 40. Quasi-Static Source Current with $V_{DD}=8V$

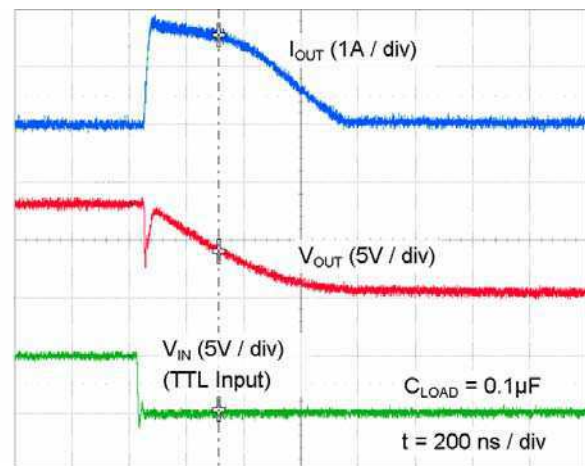


Figure 41. Quasi-Static Sink Current with $V_{DD}=8V$

Test Circuit

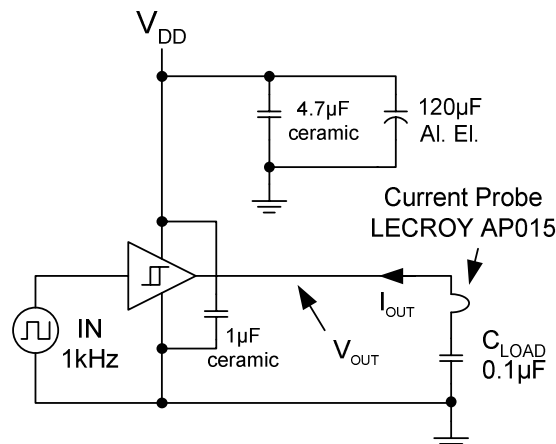


Figure 42. Quasi-Static I_{OUT} / V_{OUT} Test Circuit

Applications Information

Input Thresholds

Each member of the FAN322x driver family consists of two identical channels that may be used independently at rated current or connected in parallel to double the individual current capacity. In the FAN3226 and FAN3227, channels A and B can be enabled or disabled independently using ENA or ENB, respectively. If ENA and ENB are not connected, an internal pull-up resistor enables the driver channels by default. If the channel A and channel B inputs and outputs are connected in parallel to increase the driver current capacity, ENA and ENB should be connected and driven together.

The FAN322x family offers versions in either TTL or CMOS input thresholds. In the FAN322xT, the input thresholds meet industry-standard TTL-logic thresholds independent of the V_{DD} voltage, and there is a hysteresis voltage of approximately 0.4V. These levels permit the inputs to be driven from a range of input logic signal levels for which a voltage over 2V is considered logic high. The driving signal for the TTL inputs should have fast rising and falling edges with a slew rate of 6V/ μ s or faster, so a rise time from 0 to 3.3V should be 550ns or less. With reduced slew rate, circuit noise could cause the driver input voltage to exceed the hysteresis voltage and retrigger the driver input, causing erratic operation.

In the FAN322xC, the logic input thresholds are dependent on the V_{DD} level and, with V_{DD} of 12V, the logic rising edge threshold is approximately 55% of V_{DD} and the input falling edge threshold is approximately 38% of V_{DD} . The CMOS input configuration offers a hysteresis voltage of approximately 17% of V_{DD} . The CMOS inputs can be used with relatively slow edges (approaching DC) if good decoupling and bypass techniques are incorporated in the system design to prevent noise from violating the input voltage hysteresis window. This allows setting precise timing intervals by fitting an R-C circuit between the controlling signal and the IN pin of the driver. The slow rising edge at the IN pin of the driver introduces a delay between the controlling signal and the OUT pin of the driver.

Static Supply Current

In the static I_{DD} , typical performance characteristics (Figure 11, Figure 12, Figure 13), two curves are shown in each figure. The lower curve is produced with all inputs/enables floating (with OUT low) and indicates the lowest static I_{DD} current for the tested configuration. The upper curve has the inputs configured to set the output high (equal to V_{DD}). The difference between these curves is caused by current flowing in the 100k Ω resistors on the inputs and outputs shown in the block diagram of each part (Figure 5, Figure 6, Figure 7, and Figure 8).

MillerDrive™ Gate Drive Technology

FAN322x gate drivers incorporate the MillerDrive™ architecture shown in Figure 43. For the output stage, a combination of bipolar and MOS devices provide large currents over a wide range of supply voltage and temperature variations. The bipolar devices carry the bulk of the current as OUT swings between 1/3 to 2/3 V_{DD} and the MOS devices pull the output to the high or low rail.

The purpose of the MillerDrive™ architecture is to speed up switching by providing high current during the Miller plateau region when the gate-drain capacitance of the MOSFET is being charged or discharged as part of the turn-on / turn-off process.

For applications that have zero voltage switching during the MOSFET turn-on or turn-off interval, the driver supplies high peak current for fast switching even though the Miller plateau is not present. This situation often occurs in synchronous rectifier applications because the body diode is generally conducting before the MOSFET is switched on.

The output pin slew rate is determined by V_{DD} voltage and the load on the output. It is not user adjustable, but a series resistor can be added if a slower rise or fall time at the MOSFET gate is needed.

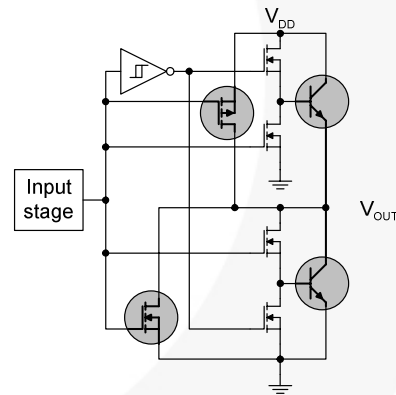


Figure 43. MillerDrive™ Output Architecture

Under-Voltage Lockout

The FAN322x start-up logic is optimized to drive ground-referenced N-channel MOSFETs with an under-voltage lockout (UVLO) function to ensure that the IC starts up in an orderly fashion. When V_{DD} is rising, yet below the 3.9V operational level, this circuit holds the output low, regardless of the status of the input pins. After the part is active, the supply voltage must drop 0.2V before the part shuts down. This hysteresis helps prevent chatter when low V_{DD} supply voltages have noise from the power switching. This configuration is not suitable for driving high-side P-channel MOSFETs because the low output voltage of the driver would turn the P-channel MOSFET on with V_{DD} below 3.9V.

VDD Bypass Capacitor Guidelines

To enable this IC to turn a device on quickly, a local high-frequency bypass capacitor C_{BYP} with low ESR and ESL should be connected between the VDD and GND pins with minimal trace length. This capacitor is in addition to bulk electrolytic capacitance of $10\mu\text{F}$ to $47\mu\text{F}$ commonly found on driver and controller bias circuits.

A typical criterion for choosing the value of C_{BYP} is to keep the ripple voltage on the V_{DD} supply to $\leq 5\%$. This is often achieved with a value ≥ 20 times the equivalent load capacitance C_{EQV} , defined here as Q_{GATE}/V_{DD} . Ceramic capacitors of $0.1\mu\text{F}$ to $1\mu\text{F}$ or larger are common choices, as are dielectrics, such as X5R and X7R with good temperature characteristics and high pulse current capability.

If circuit noise affects normal operation, the value of C_{BYP} may be increased to 50-100 times the C_{EQV} , or C_{BYP} may be split into two capacitors. One should be a larger value, based on equivalent load capacitance, and the other a smaller value, such as 1-10nF mounted closest to the VDD and GND pins to carry the higher frequency components of the current pulses. The bypass capacitor must provide the pulsed current from both of the driver channels and, if the drivers are switching simultaneously, the combined peak current sourced from the C_{BYP} would be twice as large as when a single channel is switching.

Layout and Connection Guidelines

The FAN3226-26 family of gate drivers incorporates fast-reacting input circuits, short propagation delays, and powerful output stages capable of delivering current peaks over 2A to facilitate voltage transition times from under 10ns to over 150ns. The following layout and connection guidelines are strongly recommended:

- Keep high-current output and power ground paths separate logic and enable input signals and signal ground paths. This is especially critical when dealing with TTL-level logic thresholds at driver inputs and enable pins.
- Keep the driver as close to the load as possible to minimize the length of high-current traces. This reduces the series inductance to improve high-speed switching, while reducing the loop area that can radiate EMI to the driver inputs and surrounding circuitry.
- If the inputs to a channel are not externally connected, the internal $100\text{k}\Omega$ resistors indicated on block diagrams command a low output. In noisy environments, it may be necessary to tie inputs of an unused channel to VDD or GND using short traces to prevent noise from causing spurious output switching.
- Many high-speed power circuits can be susceptible to noise injected from their own output or other external sources, possibly causing output re-triggering. These effects can be obvious if the circuit is tested in breadboard or non-optimal circuit layouts with long input, enable, or output leads. For

best results, make connections to all pins as short and direct as possible.

- The FAN322x is compatible with many other industry-standard drivers. In single input parts with enable pins, there is an internal $100\text{k}\Omega$ resistor tied to VDD to enable the driver by default; this should be considered in the PCB layout.
- The turn-on and turn-off current paths should be minimized, as discussed in the following section.

Figure 44 shows the pulsed gate drive current path when the gate driver is supplying gate charge to turn the MOSFET on. The current is supplied from the local bypass capacitor, C_{BYP} , and flows through the driver to the MOSFET gate and to ground. To reach the high peak currents possible, the resistance and inductance in the path should be minimized. The localized C_{BYP} acts to contain the high peak current pulses within this driver-MOSFET circuit, preventing them from disturbing the sensitive analog circuitry in the PWM controller.

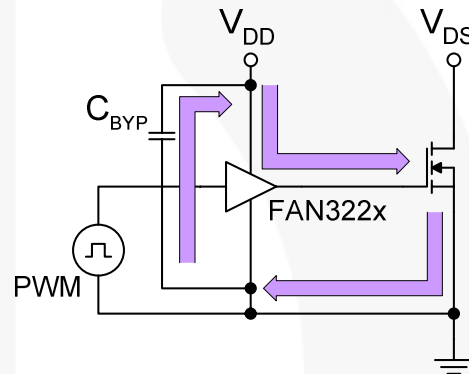


Figure 44. Current Path for MOSFET Turn-on

Figure 45 shows the current path when the gate driver turns the MOSFET off. Ideally, the driver shunts the current directly to the source of the MOSFET in a small circuit loop. For fast turn-off times, the resistance and inductance in this path should be minimized.

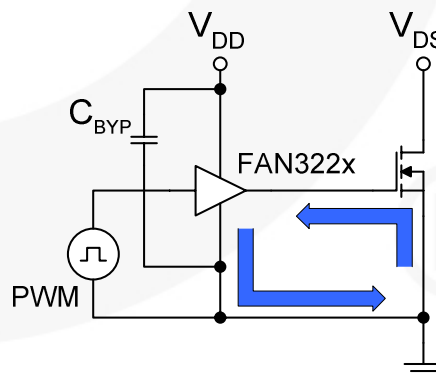


Figure 45. Current Path for MOSFET Turn-off

Truth Table of Logic Operation

The FAN3228/FAN3229 truth table indicates the operational states using the dual-input configuration. In a non-inverting driver configuration, the IN- pin should be a logic low signal. If the IN- pin is connected to logic high, a disable function is realized, and the driver output remains low regardless of the state of the IN+ pin.

IN+	IN-	OUT
0	0	0
0	1	0
1	0	1
1	1	0

In the non-inverting driver configuration in Figure 46, the IN- pin is tied to ground and the input signal (PWM) is applied to IN+ pin. The IN- pin can be connected to logic high to disable the driver and the output remains low, regardless of the state of the IN+ pin.

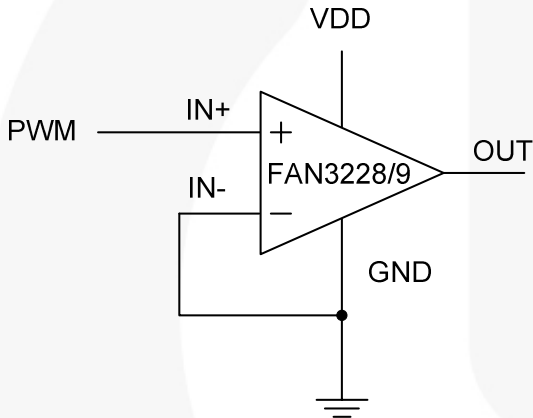


Figure 46. Dual-Input Driver Enabled, Non-Inverting Configuration

In the inverting driver application in Figure 47, the IN+ pin is tied high. Pulling the IN+ pin to GND forces the output low, regardless of the state of the IN- pin.

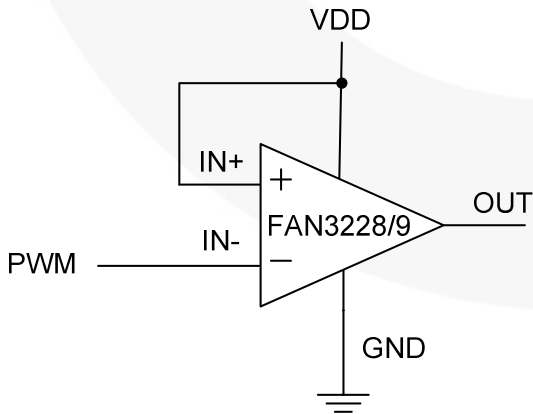


Figure 47. Dual-Input Driver Enabled, Inverting Configuration

Operational Waveforms

At power-up, the driver output remains low until the V_{DD} voltage reaches the turn-on threshold. The magnitude of the OUT pulses rises with V_{DD} until steady-state V_{DD} is reached. The non-inverting operation illustrated in Figure 48 shows that the output remains low until the UVLO threshold is reached, then the output is in-phase with the input.

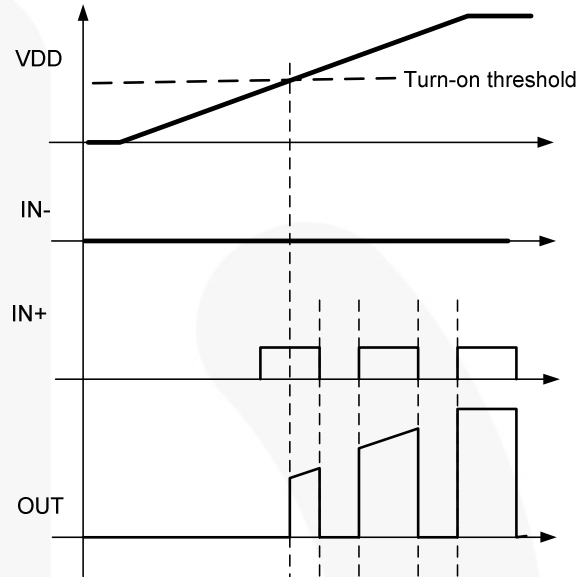


Figure 48. Non-Inverting Start-Up Waveforms

For the inverting configuration of Figure 47, start-up waveforms are shown in Figure 49. With IN+ tied to V_{DD} and the input signal applied to IN-, the OUT pulses are inverted with respect to the input. At power-up, the inverted output remains low until the V_{DD} voltage reaches the turn-on threshold, then it follows the input with inverted phase.

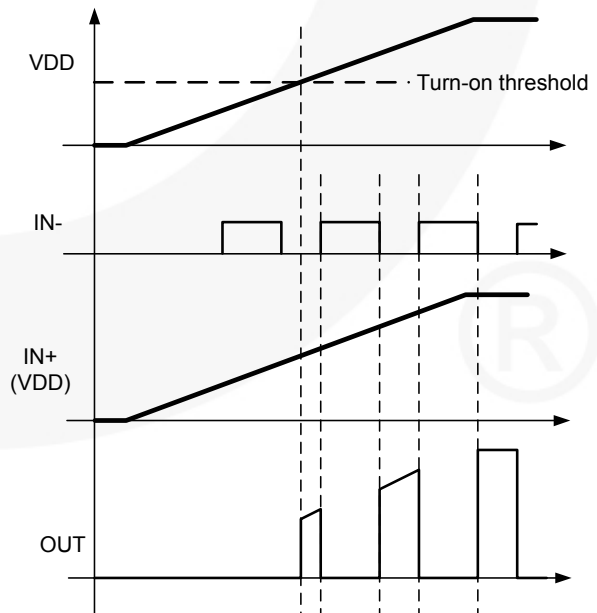


Figure 49. Inverting Start-Up Waveforms

Thermal Guidelines

Gate drivers used to switch MOSFETs and IGBTs at high frequencies can dissipate significant amounts of power. It is important to determine the driver power dissipation and the resulting junction temperature in the application to ensure that the part is operating within acceptable temperature limits.

The total power dissipation in a gate driver is the sum of two components, P_{GATE} and $P_{DYNAMIC}$:

$$P_{TOTAL} = P_{GATE} + P_{DYNAMIC} \quad (1)$$

Gate Driving Loss: The most significant power loss results from supplying gate current (charge per unit time) to switch the load MOSFET on and off at the switching frequency. The power dissipation that results from driving a MOSFET at a specified gate-source voltage, V_{GS} , with gate charge, Q_G , at switching frequency, F_{SW} , is determined by:

$$P_{GATE} = Q_G \cdot V_{GS} \cdot F_{SW} \cdot n \quad (2)$$

n is the number of driver channels in use (1 or 2).

Dynamic Pre-drive / Shoot-through Current: A power loss resulting from internal current consumption under dynamic operating conditions, including pin pull-up / pull-down resistors, can be obtained using the graphs in Typical Performance Characteristics to determine the current $I_{DYNAMIC}$ drawn from V_{DD} under actual operating conditions:

$$P_{DYNAMIC} = I_{DYNAMIC} \cdot V_{DD} \cdot n \quad (3)$$

Once the power dissipated in the driver is determined, the driver junction rise with respect to circuit board can be evaluated using the following thermal equation, assuming Ψ_{JB} was determined for a similar thermal design (heat sinking and air flow):

$$T_J = P_{TOTAL} \cdot \Psi_{JB} + T_B \quad (4)$$

where:

T_J = driver junction temperature

Ψ_{JB} = (psi) thermal characterization parameter relating temperature rise to total power dissipation

T_B = board temperature in location defined in Note 1 under Thermal Resistance table.

In the forward converter with synchronous rectifier shown in the typical application diagrams, the FDMS8660S is a reasonable MOSFET selection. The gate charge for each SR MOSFET would be 60nC with $V_{GS} = V_{DD} = 7V$. At a switching frequency of 500kHz, the total power dissipation is:

$$P_{GATE} = 60\text{nC} \cdot 7V \cdot 500\text{kHz} \cdot 2 = 0.42W \quad (5)$$

$$P_{DYNAMIC} = 3\text{mA} \cdot 7V \cdot 2 = 0.042W \quad (6)$$

$$P_{TOTAL} = 0.46W \quad (7)$$

The SOIC-8 has a junction-to-board thermal characterization parameter of $\Psi_{JB} = 43^\circ\text{C/W}$. In a system application, the localized temperature around the device is a function of the layout and construction of the PCB along with airflow across the surfaces. To ensure reliable operation, the maximum junction temperature of the device must be prevented from exceeding the maximum rating of 150°C ; with 80% derating, T_J would be limited to 120°C . Rearranging Equation 4 determines the board temperature required to maintain the junction temperature below 120°C :

$$T_B = T_J - P_{TOTAL} \cdot \Psi_{JB} \quad (8)$$

$$T_B = 120^\circ\text{C} - 0.46W \cdot 43^\circ\text{C/W} = 100^\circ\text{C} \quad (9)$$

For comparison, replace the SOIC-8 used in the previous example with the 3x3mm MLP package with $\Psi_{JB} = 3.5^\circ\text{C/W}$. The 3x3mm MLP package could operate at a PCB temperature of 118°C , while maintaining the junction temperature below 120°C . This illustrates that the physically smaller MLP package with thermal pad offers a more conductive path to remove the heat from the driver. Consider tradeoffs between reducing overall circuit size with junction temperature reduction for increased reliability.



Typical Application Diagrams

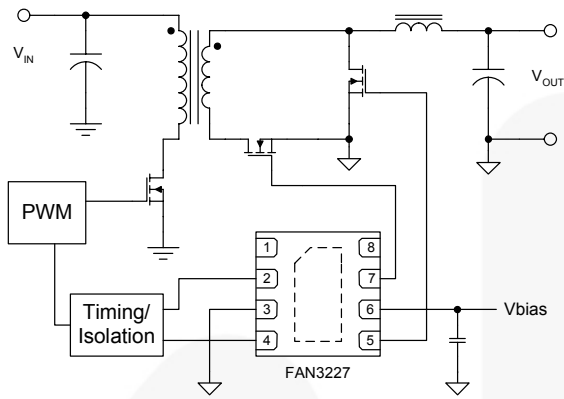


Figure 50. Forward Converter with Synchronous Rectification

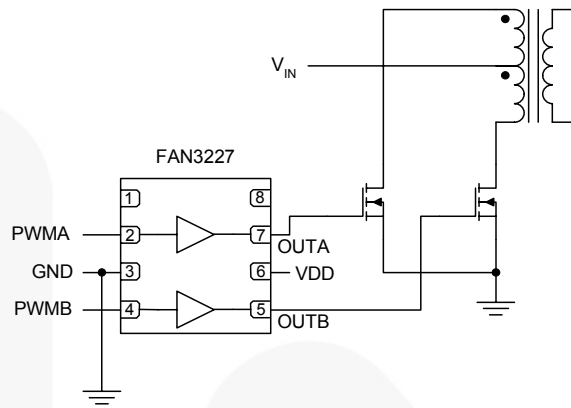


Figure 51. Primary-side Dual Driver in a Push-pull Converter

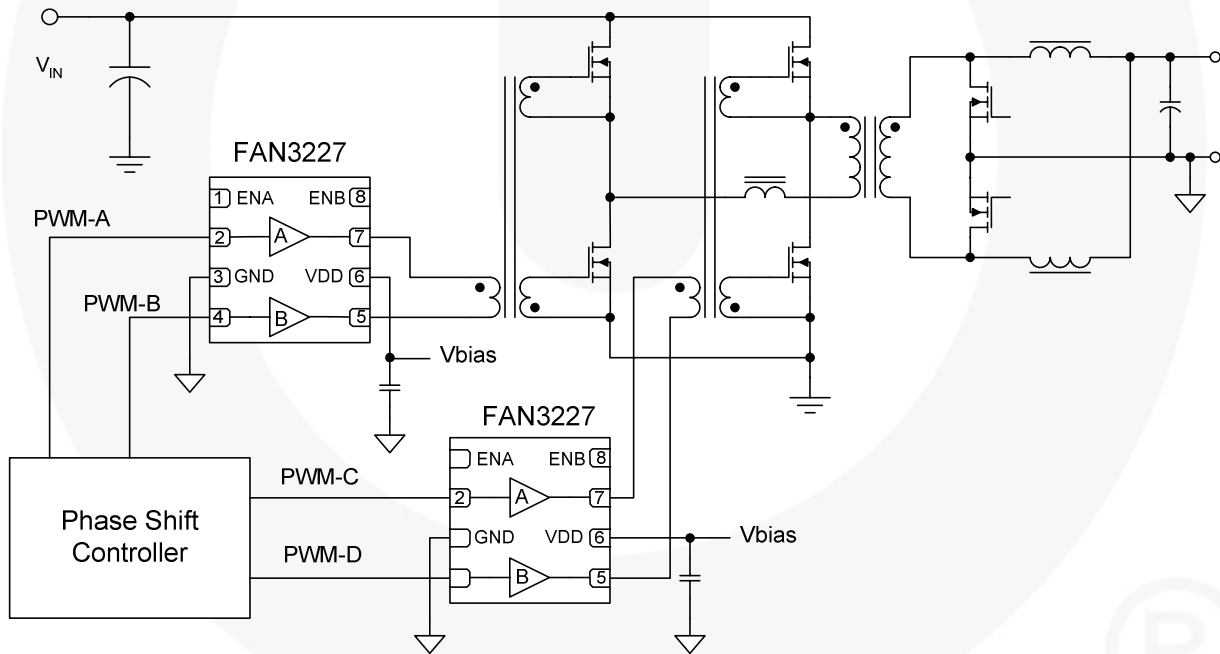


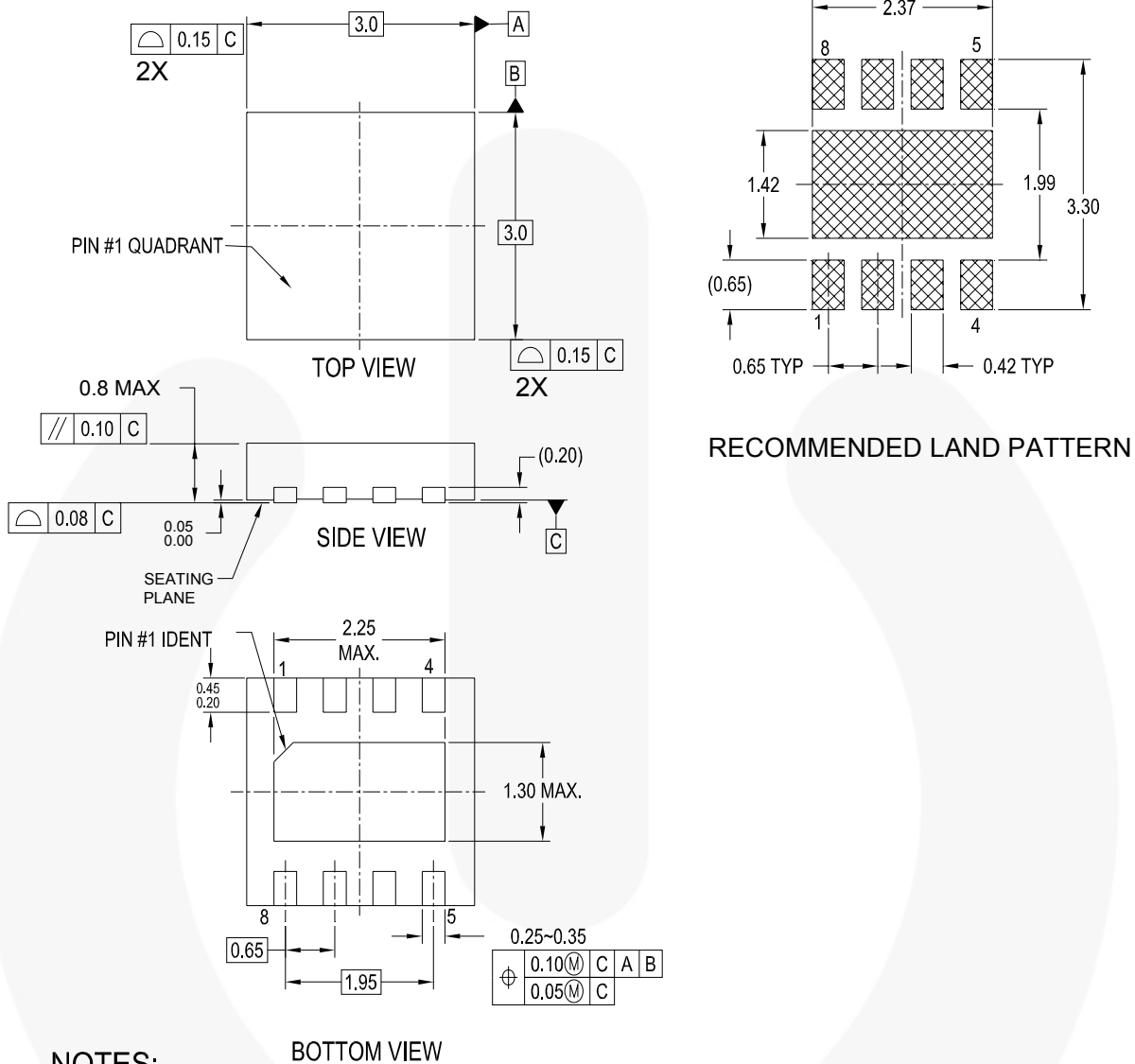
Figure 52. Phase-shifted Full-bridge with Two Gate Drive Transformers (Simplified)

Table 1. Related Products

Part Number	Type	Gate Drive ⁽¹⁾ (Sink/Src)	Input Threshold	Logic	Package
FAN3100C	Single 2A	+2.5A / -1.8A	CMOS	Single Channel of Two-Input/One-Output	SOT23-5, MLP6
FAN3100T	Single 2A	+2.5A / -1.8A	TTL	Single Channel of Two-Input/One-Output	SOT23-5, MLP6
FAN3226C	Dual 2A	+2.4A / -1.6A	CMOS	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3226T	Dual 2A	+2.4A / -1.6A	TTL	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3227C	Dual 2A	+2.4A / -1.6A	CMOS	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3227T	Dual 2A	+2.4A / -1.6A	TTL	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3228C	Dual 2A	+2.4A / -1.6A	CMOS	Dual Channels of Two-Input/One-Output, Pin Config.1	SOIC8, MLP8
FAN3228T	Dual 2A	+2.4A / -1.6A	TTL	Dual Channels of Two-Input/One-Output, Pin Config.1	SOIC8, MLP8
FAN3229C	Dual 2A	+2.4A / -1.6A	CMOS	Dual Channels of Two-Input/One-Output, Pin Config.2	SOIC8, MLP8
FAN3229T	Dual 2A	+2.4A / -1.6A	TTL	Dual Channels of Two-Input/One-Output, Pin Config.2	SOIC8, MLP8
FAN3223C	Dual 4A	+4A / -3A	CMOS	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3223T	Dual 4A	+4A / -3A	TTL	Dual Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3224C	Dual 4A	+4A / -3A	CMOS	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3224T	Dual 4A	+4A / -3A	TTL	Dual Non-Inverting Channels + Dual Enable	SOIC8, MLP8
FAN3225C	Dual 4A	+4A / -3A	CMOS	Dual Channels of Two-Input/One-Output	SOIC8, MLP8
FAN3225T	Dual 4A	+4A / -3A	TTL	Dual Channels of Two-Input/One-Output	SOIC8, MLP8

Note:11. Typical currents with OUT at 6V and $V_{DD} = 12V$.

Physical Dimensions



NOTES:

- CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VEEC, DATED 11/2001
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- FILENAME: MKT-MLP08Drev2

Figure 53. 3x3mm, 8-Lead Molded Leadless Package (MLP)

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Physical Dimensions (Continued)

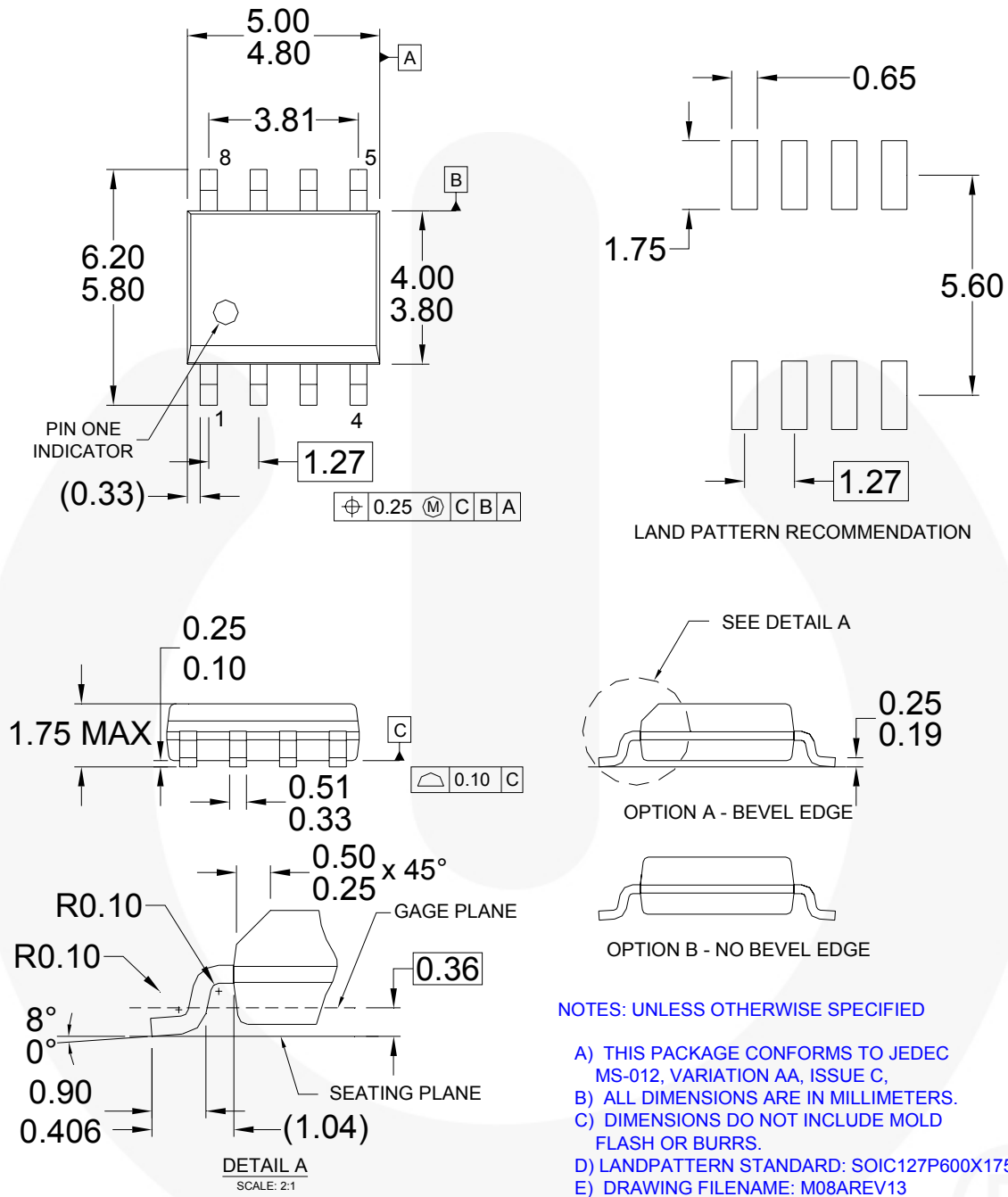


Figure 54. 8-Lead SOIC

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